

- Integrated 0.15-Ω Power MOSFET
- 3-V to 8-V Operation
- Digital Programmable Current Limit from 0 A to 3 A
- Electronic Circuit Breaker Function
- 1μA I<sub>CC</sub> When Disabled
- Programmable On-Time
- Programmable Start Delay
- Fixed 3% Duty Cycle
- Unidirectional Switch
- Thermal Shutdown
- Fault-Output Indicator
- Maximum-Output Current Can Be Set to 1 A Above the Programmed Fault Level or to a Full 4 A
- Power SOIC, Low-Thermal Resistance Packaging

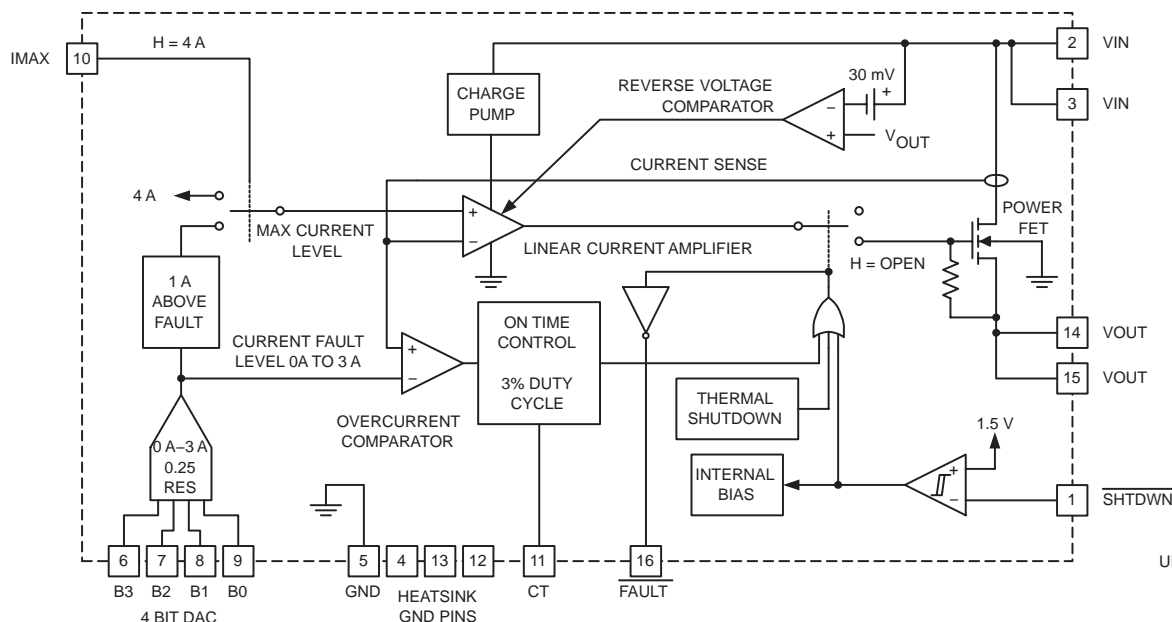
**description**

The UCC3912 family of hot swap power managers provides complete power management, hot swap capability, and circuit breaker functions. The only component required to operate the device, other than supply bypassing, is the fault timing capacitor, C<sub>T</sub>. All control and housekeeping functions are integrated, and externally programmable. These include the fault current level, maximum output-sourcing current, maximum fault time, and startup delay. In the event of a constant fault, the internal fixed 3% duty cycle ratio limits average output power.

The internal 4-bit DAC allows programming of the fault level current from 0 A to 3 A with 0.25-A resolution. The IMAX control pin sets the maximum sourcing current to 1 A above the fault level when driven low, and to a full 4 A when driven high for applications which require fast output capacitor charging.

When the output current is below the fault level, the output MOSFET is switched on with a nominal on resistance of 0.15 Ω. When the output current exceeds the fault level, but is less than the maximum sourcing level, the output remains switched on, but the fault timer starts charging C<sub>T</sub>. Once C<sub>T</sub> charges to a preset threshold, the switch is turned off, and remains off for 30 times the programmed fault time. When the output current reaches the maximum sourcing level, the MOSFET transitions from a switch to a constant current source. (continued)

**block diagram**



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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# UCC2912 UCC3912 PROGRAMMABLE HOT SWAP POWER MANAGER

SLUS241D – MARCH 1994 - REVISED NOVEMBER 2003

## description (continued)

The UCC3912 family is designed for unidirectional current flow, emulating an ideal diode in series with the power switch. This feature is particularly attractive in applications where many devices are powering a common bus, such as with SCSI Termpwr.

The UCC3912 family can be put into sleep mode drawing only 1- $\mu$ A of supply current. The  $\overline{\text{SHTDWN}}$  pin has a preset threshold hysteresis which allows the user the ability to set a time delay upon startup to achieve sequencing of power. Other features include an open drain  $\overline{\text{FAULT}}$  output indicator, thermal shutdown, under voltage lockout, and a low thermal resistance small outline package.

## absolute maximum ratings over operating free-air temperature (unless otherwise noted)<sup>†‡</sup>

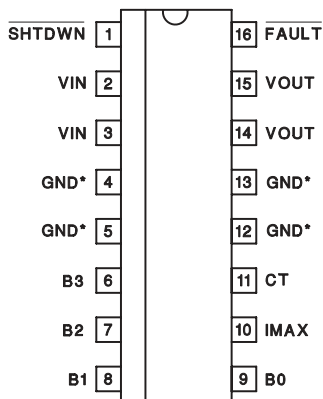
VIN	8 V
$\overline{\text{FAULT}}$ sink current	50 mA
$\overline{\text{FAULT}}$ voltage	-0.3 to VIN
Output current	Self Limiting
Input voltage (B0, B1, B2, B3, IMAX, $\overline{\text{SHTDWN}}$ )	-0.3 to VIN
Storage temperature range, T <sub>stg</sub>	-65°C to 150°C
Operating junction temperature range, T <sub>J</sub>	-55°C to 150°C
Lead temperature (soldering, 10 sec.)	300°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

<sup>‡</sup> Currents are positive into, negative out of the specified terminal. Consult Packaging Section of the Interface Products Data book (TI Literature Number SLUD002) for thermal limitations and considerations of packages.

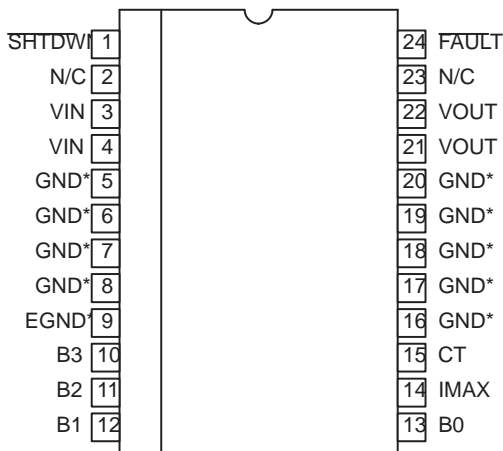
## package information

**DIL-16, SOIC-16  
N, DP Package  
(TOP VIEW)**



\*Pin 5 serves as lowest impedance to the electrical ground; Pins 4, 12, and 13 serve as heat sink/ground. These pins should be connected to large etch areas to help dissipate heat. For N package, pins 4, 12, and 13 are N/C.

**TSSOP-24,  
PWP Package  
(TOP VIEW)**



\*Pin 9 serves as lowest impedance to the electrical ground; other GND pins serve as heat sink/ground. These pins should be connected to large etch areas to help dissipate heat.

PROGRAMMABLE HOT SWAP POWER MANAGER

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electrical characteristics, these specifications apply for  $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  for the UCC2912;  $T_A = 0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$  for the UCC3912,  $V_{IN} = 5\text{ V}$ ,  $I_{MAX} = 0.4\text{ V}$ ,  $SHTDWN = 2.4\text{ V}$  (unless otherwise stated)

supply section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Voltage input range		3.0		8.0	V
Supply current			1.0	2.0	mA
Sleep mode current	$SHTDWN = 0.2\text{ V}$		0.5	5.0	$\mu\text{A}$

NOTE 1: All voltages are with respect to ground. Current is positive into and negative out of the specified terminal.

output section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Voltage drop	$I_{OUT} = 1\text{ A}$		0.15	0.22	V
	$I_{OUT} = 2\text{ A}$		0.3	0.45	V
	$I_{OUT} = 3\text{ A}$		0.45	0.68	V
	$I_{OUT} = 1\text{ A}$ , $V_{IN} = 3\text{ V}$		0.17	0.27	V
	$I_{OUT} = 2\text{ A}$ , $V_{IN} = 3\text{ V}$		0.35	0.56	V
	$I_{OUT} = 3\text{ A}$ , $V_{IN} = 3\text{ V}$		0.5	0.8	V
Reverse leakage current	$V_{IN} < V_{OUT}$ , $SHTDWN = 0.2\text{ V}$ , $V_{OUT} = 5\text{ V}$		5	20	$\mu\text{A}$
Initial startup time	See Note 2		100		$\mu\text{s}$
Short circuit response	See Note 2		100		ns
Thermal shutdown	See Note 2		170		$^{\circ}\text{C}$
Thermal hysteresis	See Note 2		10		$^{\circ}\text{C}$

NOTE 1: All voltages are with respect to ground. Current is positive into and negative out of the specified terminal.

NOTE 2: Ensured by design. Not production tested.

DAC section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
Output leakage	Code = 0000–0011		0	20	$\mu\text{A}$	
Trip current	Code = 0100	0.1	0.25	0.45	A	
	Code = 0101	0.25	0.50	0.75	A	
	Code = 0110	0.5	0.75	1.0	A	
	Code = 0111	0.75	1.00	1.25	A	
	Code = 1000	1.0	1.25	1.5	A	
	Code = 1001	1.25	1.50	1.75	A	
	Code = 1010	1.5	1.75	2.0	A	
	Code = 1011	1.7	2.00	2.3	A	
	Code = 1100	1.9	2.25	2.58	A	
	Code = 1101	2.1	2.50	2.9	A	
	Code = 1110	2.3	2.75	3.2	A	
	Code = 1111	2.5	3.0	3.5	A	
Maximum output current	Code = 0000 to 0011			0.02	mA	
Maximum output current over trip (current source mode)	UCC2912	Code = 0100 to 1111, $I_{MAX} = 0\text{ V}$	0.5	1.0	2.0	A
	UCC3912	Code = 0100 to 1111, $I_{MAX} = 0\text{ V}$	0.5	1.0	1.8	A
Maximum output current (current source mode)	Code = 0100 to 1111, $I_{MAX} = 2.4\text{ V}$	3.0	4.0	5.2	A	

NOTE 1: All voltages are with respect to ground. Current is positive into and negative out of the specified terminal.

# UCC2912 UCC3912 PROGRAMMABLE HOT SWAP POWER MANAGER

SLUS241D – MARCH 1994 - REVISED NOVEMBER 2003

electrical characteristics, these specifications apply for  $T_A = -40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$  for the UCC2912;  $T_A = 0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$  for the UCC3912,  $V_{IN} = 5\text{ V}$ ,  $I_{MAX} = 0.4\text{ V}$ ,  $SHTDWN = 2.4\text{ V}$  (unless otherwise stated)

## timer section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
CT charge current	$V_{CT} = 1.0\text{ V}$	-45.0	-36.0	-22.0	$\mu\text{A}$
CT discharge current	UCC2912 $V_{CT} = 1.0\text{ V}$	0.72	1.20	1.57	$\mu\text{A}$
	UCC3912 $V_{CT} = 1.0\text{ V}$	0.72	1.20	1.50	$\mu\text{A}$
Output duty cycle	$V_{OUT} = 0\text{ V}$	2.0	3.0	6.0	%
CT fault threshold		1.3	1.5	1.7	V
CT reset threshold		0.4	0.5	0.6	V

NOTE 1: All voltages are with respect to ground. Current is positive into and negative out of the specified terminal.

## shutdown section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Shutdown threshold		1.1	1.5	1.9	V
Shutdown hysteresis			100		mV
Input current	$SHTDWN = 1\text{ V}$		100	500	nA

## fault output section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Output leakage current				500	nA
Low level output voltage	$I_{OUT} = 10\text{ mA}$		0.4	0.8	V

## TTL input dc characteristics section

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
TTL input voltage high	(can be connected to $V_{IN}$ )	2.0			V
TTL input voltage low				0.8	V
TTL input high current	$V_{IH} = 2.4\text{ V}$		3	10	$\mu\text{A}$
TTL input low current	$V_{IL} = 0.4\text{ V}$			1	$\mu\text{A}$

NOTE 1: All voltages are with respect to ground. Current is positive into and negative out of the specified terminal.

## pin description

**B0–B3:** These pins provide digital input to the DAC which sets the fault current threshold. They can be used to provide a digital soft-start, adaptive current limiting.

**CT:** A capacitor connected to ground sets the maximum fault time. The maximum fault time must be more than the time to charge the external capacitance in one cycle. The maximum fault time is defined as  $FAULT = 27.8 \times 10^3 \times CT$ . Once the fault time is reached the output will shutdown for a time given by:  $T_{SD} = 833 \times 10^3 \times CT$ , this equates to a 3% duty cycle.

**FAULT:** Open drain output which pulls low upon any condition which causes the output to open: fault, thermal shutdown, or shutdown.

**IMAX:** When this pin is set to logic low the maximum sourcing current will always be 1 A above the programmed fault level. When set to logic high, the maximum sourcing current will be a constant 4 A for applications which require fast charging of load capacitance.

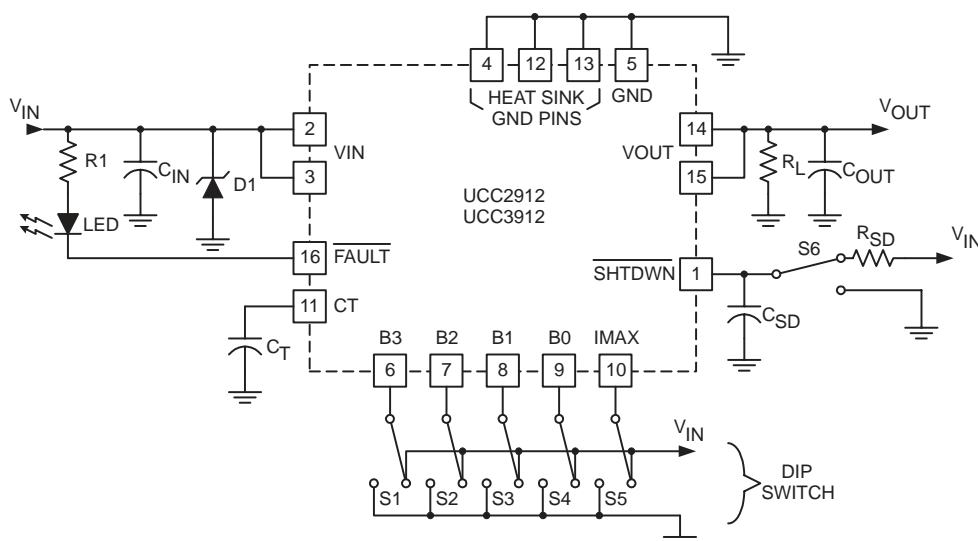
**pin description (continued)**

**SHTDWN:** When this pin is brought to a logic low, the IC is put into a sleep mode drawing typically less than 1  $\mu$ A of  $I_{CC}$ . The input threshold is hysteretic, allowing the user to program a startup delay with an external RC circuit.

**VIN:** Input voltage to the UCC3912. The recommended voltage range is 3 V to 8 V. Both VIN pins should be connected together and to the power source.

**VOUT:** Output voltage from the UCC3912. When switched the output voltage will be approximately  $V_{IN} - (0.15 \Omega \times I_{OUT})$ . Both VOUT pins should be connected together and to the load.

**APPLICATION INFORMATION**



NOTE: For demonstration board schematic see Design Note DN-58 (TI Literature Number SLUA187).

UDG-99171

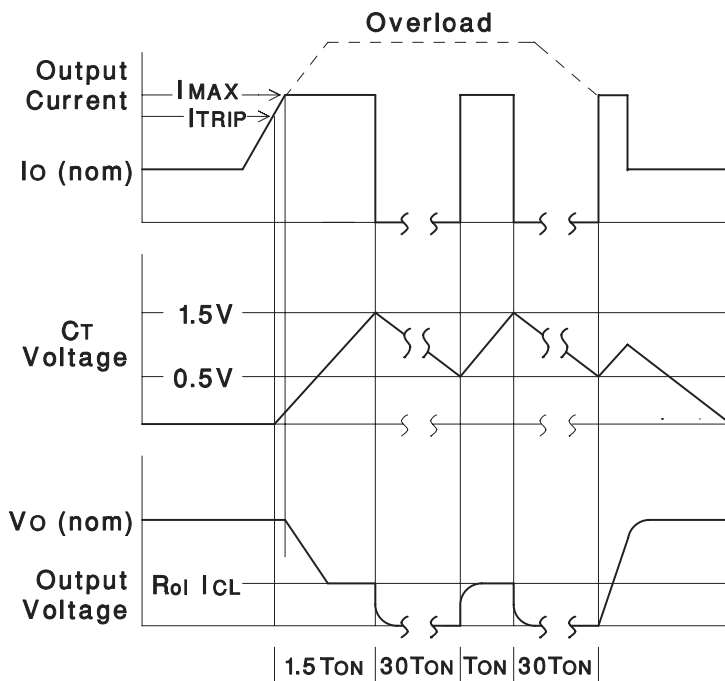
**Figure 1. Evaluation Circuit**

**protecting the UCC3912 from voltage transients**

The parasitic inductance associated with the power distribution can cause a voltage spike at  $V_{IN}$  if the load current is suddenly interrupted by the UCC3912. It is important to limit the peak of this spike to less than 8 V to prevent damage to the UCC3912. This voltage spike can be minimized by:

- Reducing the power distribution inductance (e.g., twist the positive and negative leads of the power supply feeding  $V_{IN}$ , locate the power supply close to the UCC3912, use a PCB ground plane,...etc.).
- Decoupling  $V_{IN}$  with a capacitor,  $C_{IN}$  (refer to Figure 1), located close to pins 2 and 3. This capacitor is typically less than 1  $\mu$ F to limit the inrush current.
- Clamping the voltage at  $V_{IN}$  below 8 V with a zener diode, D1 (refer to Figure 1), located close to pins 2 and 3.

**APPLICATION INFORMATION**



UDG-93019-4

**Figure 2. Load Current, Timing-Capacitor Voltage, and Output Voltage of the UCC3912 Under Fault Conditions.**

**estimating maximum load capacitance**

For hot-swap applications, the rate at which the total output capacitance can be charged depends on the maximum output current available and the nature of the load. For a constant-current current-limited controller, the output will come up if the load asks for less than the maximum available short-circuit current.

To ensure recovery of a duty-cycle from a short-circuited load condition, there is a maximum total output capacitance which can be charged for a given unit ON time (fault time). The design value of ON or fault time can be adjusted by changing the timing capacitor  $C_T$ .

For worst-case constant-current load of value just less than the trip limit;  $C_{OUT(max)}$  can be estimated from:

$$C_{OUT(max)} \approx (I_{MAX} - I_{LOAD}) \times \left( \frac{28 \times 10^3 \times C_T}{V_{OUT}} \right)$$

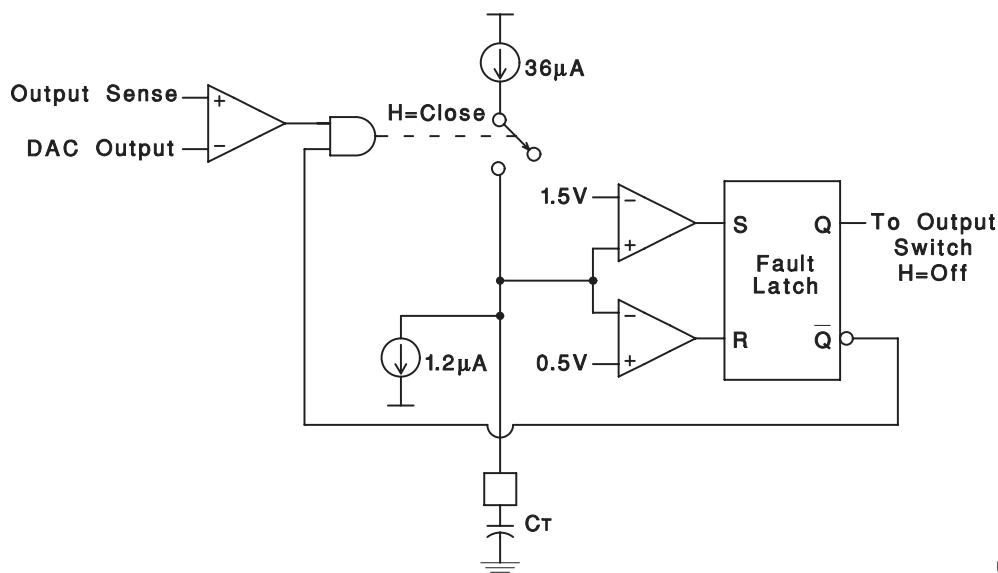
where  $V_{OUT}$  is the output voltage.

APPLICATION INFORMATION

For a resistive load of value  $R_L$ , the value of  $C_{OUT(max)}$  can be estimated from:

$$C_{OUT(max)} \approx \left[ \frac{28 \times 10^3 \times C_T}{R_L \times \ln \left[ \frac{1}{1 - \left( \frac{V_{OUT}}{I_{MAX} \times R_L} \right)} \right]} \right]$$

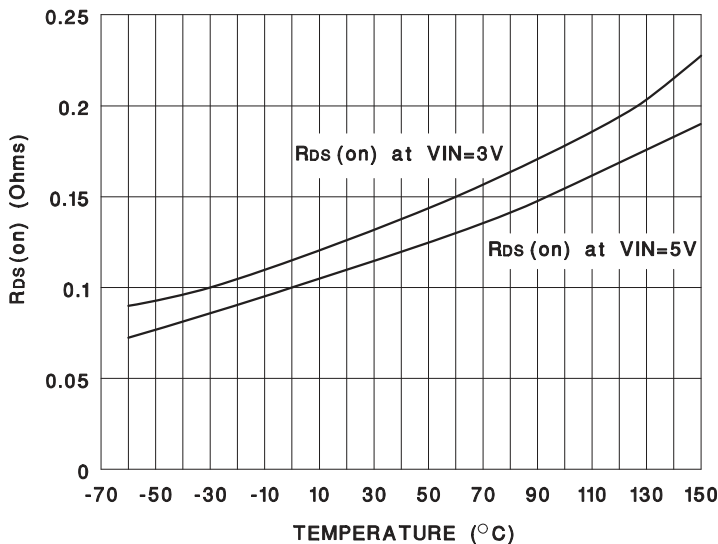
The overcurrent comparator senses both the DAC output and a representation of the output current. When the output current exceeds the programmed level the timing capacitor  $C_T$  charges with  $36 \mu A$  of current. If the fault occurs for the time it takes for  $C_T$  to charge up to 1.5 V, the fault latch is set and the output switch is opened. The output remains opened until  $C_T$  discharges to 0.5 V with a  $1.2\text{-}\mu A$  current source. Once the 0.5 V is reached the output is enabled and will either appear as a switch, if the fault is removed, or a current source if the fault remains. If the over current condition is still present, then  $C_T$  will begin charging, starting the cycle over, resulting in approximately a 3% on time.



UDG-94019-1

Figure 3. UCC3912 On-Time Circuitry

**APPLICATION INFORMATION**



UDG-94019-1

**Figure 4. R<sub>DS(on)</sub> vs. Temperature at 2-A Load Current.**

**safety recommendations**

Although the UCC3912 family is designed to provide system protection for all fault conditions, all integrated circuits can ultimately fail short. For this reason, if the UCC3912 is intended for use in safety critical applications where UL or some other safety rating is required, a redundant safety device such as a fuse should be placed in series with the device. The UCC3912 will prevent the fuse from blowing virtually for all fault conditions, increasing system reliability and reducing maintenance cost, in addition to providing the hot swap benefits of the device.



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
UCC2912DP	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UCC2912DP	<a href="#">Samples</a>
UCC2912PWP	ACTIVE	TSSOP	PW	24	60	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	UCC2912PWP	<a href="#">Samples</a>
UCC3912DP	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC3912DP	<a href="#">Samples</a>
UCC3912PWP	ACTIVE	TSSOP	PW	24	60	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC3912PWP	<a href="#">Samples</a>
UCC3912PWPG4	ACTIVE	TSSOP	PW	24	60	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC3912PWP	<a href="#">Samples</a>
UCC3912PWPTR	ACTIVE	TSSOP	PW	24	2000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	0 to 70	UCC3912PWP	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

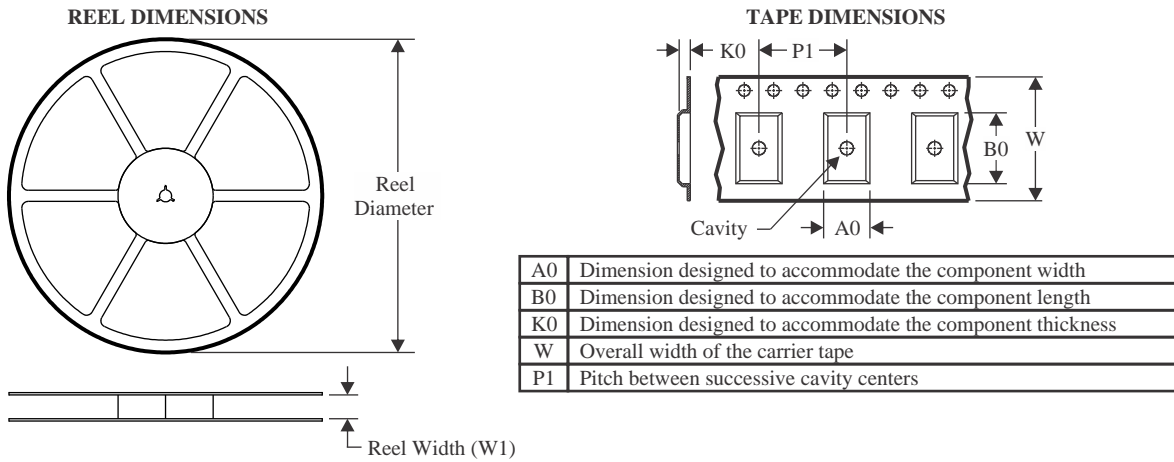
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UCC3912PWPTR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UCC3912PWPTR	TSSOP	PW	24	2000	356.0	356.0	35.0

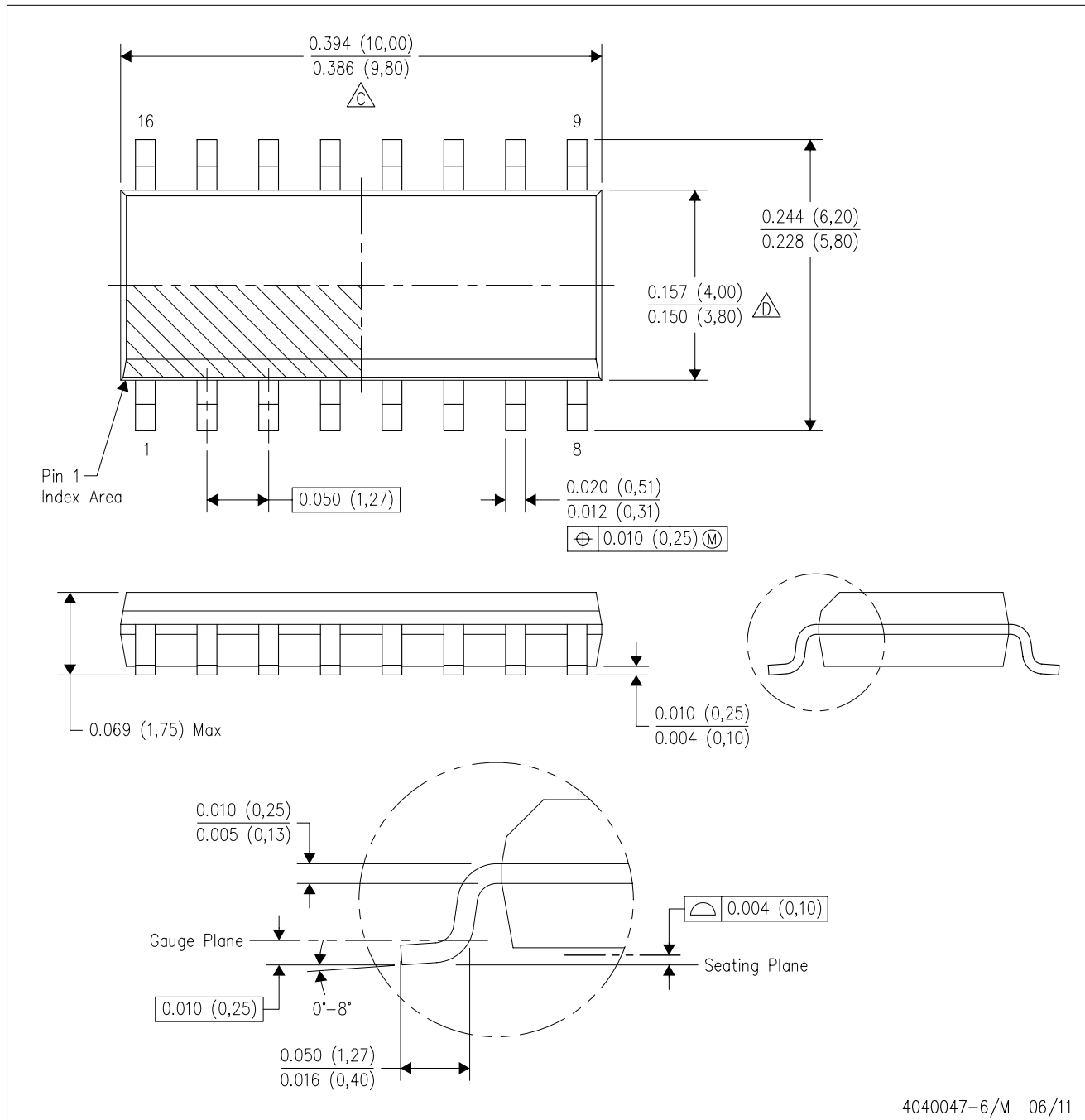
**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
UCC2912DP	D	SOIC	16	40	506.6	8	3940	4.32
UCC2912PWP	PW	TSSOP	24	60	530	10.2	3600	3.5
UCC3912DP	D	SOIC	16	40	506.6	8	3940	4.32
UCC3912PWP	PW	TSSOP	24	60	530	10.2	3600	3.5
UCC3912PWPG4	PW	TSSOP	24	60	530	10.2	3600	3.5

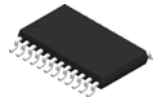
D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

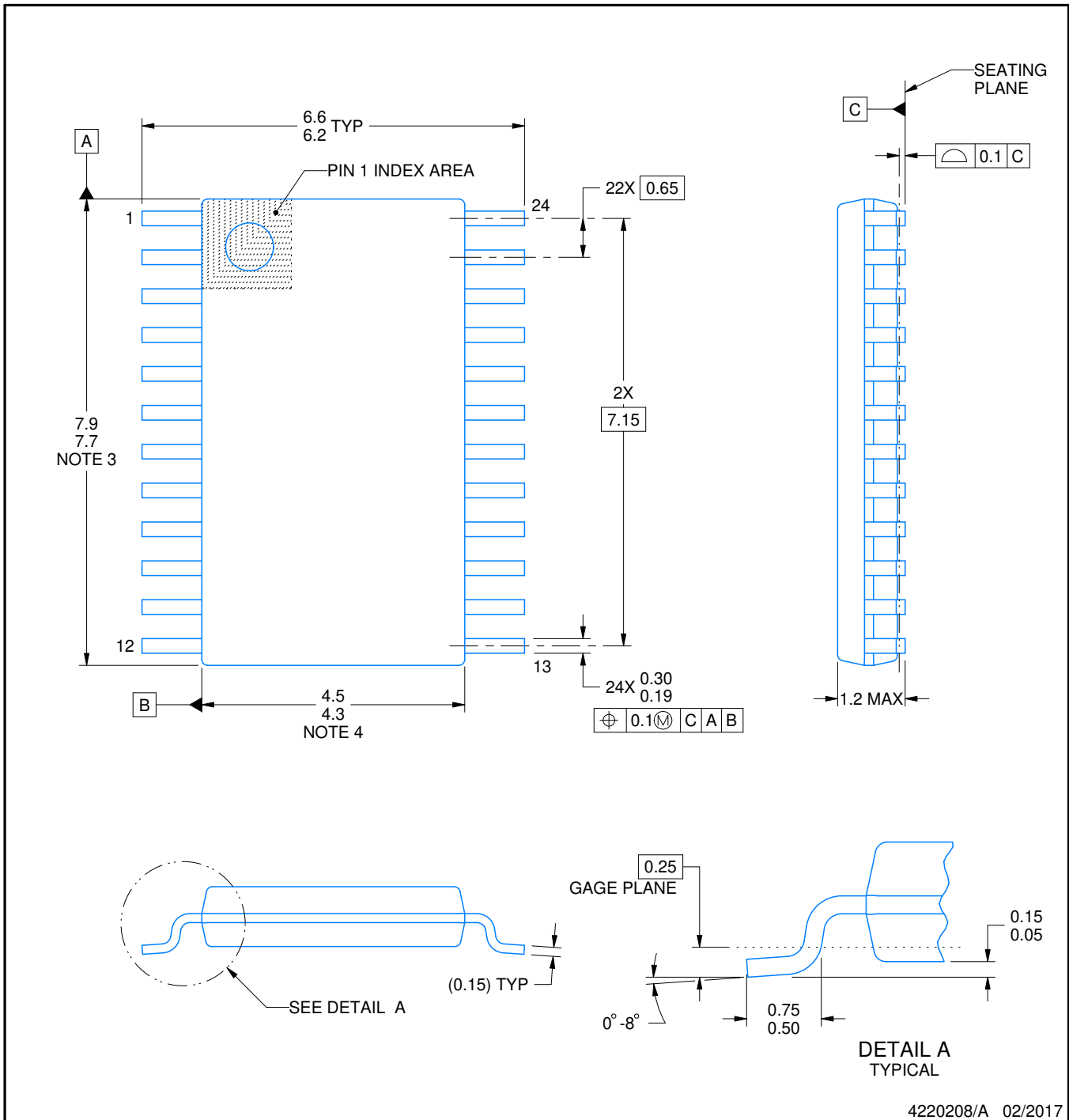
PW0024A



# PACKAGE OUTLINE

## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220208/A 02/2017

### NOTES:

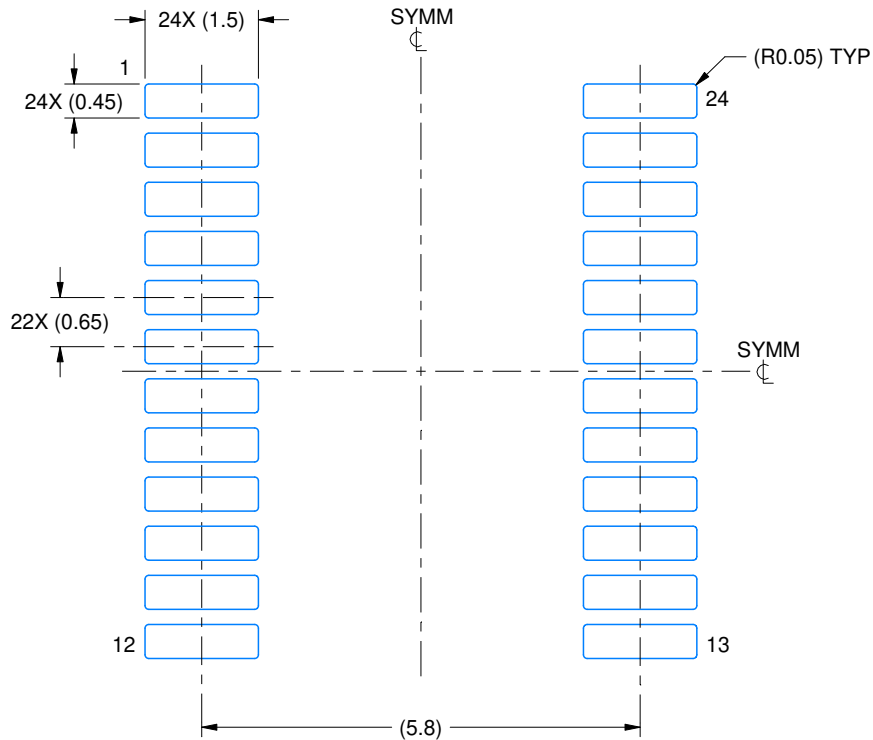
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

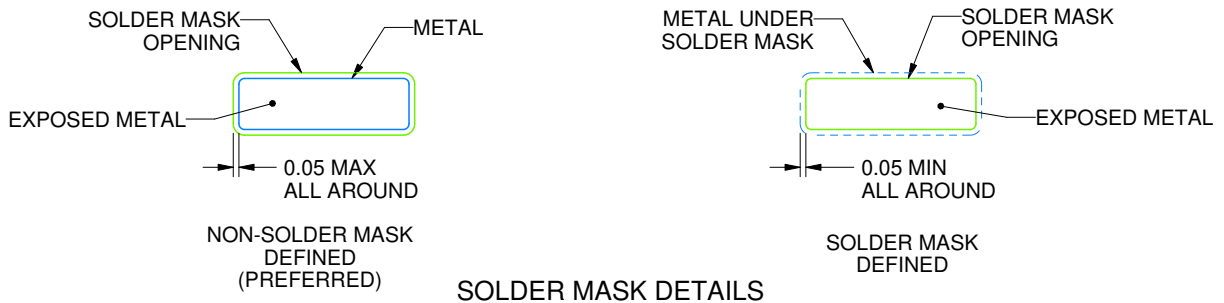
PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

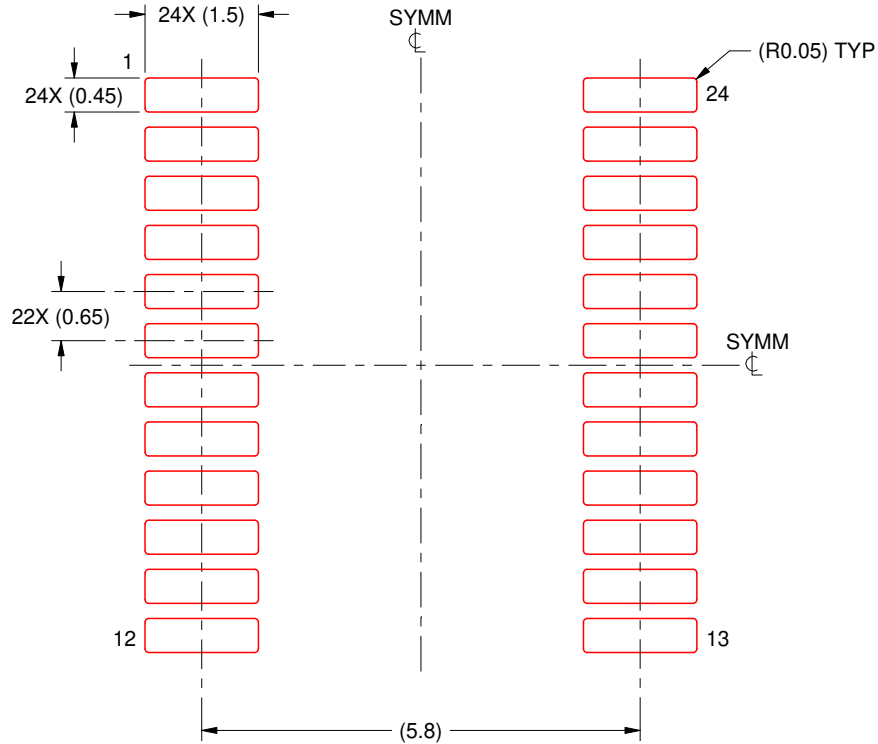


# EXAMPLE STENCIL DESIGN

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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